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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/087,432	03/01/2002	Sung-Fei Wang	U 013887-9	3547
75	90 02/23/2005		EXAMINER	
Ladas & Parry			MITCHELL, JAMES M	
26 West 61st Street New York, NY 10023			ART UNIT	PAPER NUMBER
2.000 2.000, 2.12			2813	
			DATE MAILED: 02/23/2005	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)			
Office Action Summary		10/087,432	WANG ET AL.			
		Examiner	Art Unit			
		James M. Mitchell	2813			
Period fo	The MAILING DATE of this communication ap or Reply	ppears on the cover sheet with the c	orrespondence address			
A SH THE - Exter after - If the - If NO - Failu Any	ORTENED STATUTORY PERIOD FOR REPI MAILING DATE OF THIS COMMUNICATION nsions of time may be available under the provisions of 37 CFR 1. SIX (6) MONTHS from the mailing date of this communication. It period for reply specified above is less than thirty (30) days, a rejudition of the provision of the maximum statutory period are to reply within the set or extended period for reply will, by statused the provision of the mailing of the provision of the provis	136(a). In no event, however, may a reply be timely within the statutory minimum of thirty (30) days will apply and will expire SIX (6) MONTHS from the cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).			
Status						
1)[🛛	Responsive to communication(s) filed on 26 i	November 2004.				
2a)⊠	This action is FINAL . 2b) This	is action is non-final.				
3)□	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposit	ion of Claims		•			
5)⊠ 6)⊠ 7)□	Claim(s) <u>5-11</u> is/are pending in the application 4a) Of the above claim(s) is/are withdra Claim(s) <u>5-10</u> is/are allowed. Claim(s) <u>11</u> is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and/	awn from consideration.				
Applicati	ion Papers		•			
10)	The specification is objected to by the Examina The drawing(s) filed on is/are: a) ac Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct The oath or declaration is objected to by the E	ccepted or b) objected to by the less of t	e 37 CFR 1.85(a). ected to. See 37 CFR 1.121(d).			
·	ınder 35 U.S.C. § 119					
12)□ a)l	Acknowledgment is made of a claim for foreig All b) Some * c) None of: 1. Certified copies of the priority documer 2. Certified copies of the priority documer 3. Copies of the certified copies of the priority documer application from the International Burea See the attached detailed Office action for a lis	nts have been received. Its have been received in Applicationity documents have been received au (PCT Rule 17.2(a)).	on No ed in this National Stage			
Attachmen	t(s)					
1) Notic	e of References Cited (PTO-892)	4) Interview Summary				
3) 🔲 Inform	e of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449 or PTO/SB/08 r No(s)/Mail Date	Paper No(s)/Mail Da 3) Notice of Informal P 6) Other:	ate atent Application (PTO-152)			

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DETAILED ACTION

This office action is in response to applicant's amendment filed November 26, 2004.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 11 is rejected under 35 U.S.C. 102(e) as being anticipated by Kamei et al. (U.S. 2001/0008306)

Kamei (Fig 1, 2) discloses a stacked semiconductor chip package comprising: a substrate (72,73,13) having a top surface, a first chip (3) on the top surface of the substrate and electrically connected to the substrate (Par 0032; wiring on substrate), a second chip (4) disposed above the first chip and electrically connected to the substrate (Par .0032) and having two opposed longitudinal sides defining a first length (Fig 2); and a plate (61) between the first chip and the second chip, connected (i.e. underfill not labeled on first chip and adhesive, 27) to the first chip and the second chip, and having two opposed longitudinal sides corresponding to the two longitudinal sides of the second chip, the plate defining a

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second length, the second length being larger than the first length (i.e. plate is larger than chip) to expose the opposed longitudinal sides of the plate and to expose a adhesive layer formed between the plate and the second chip (sides and adhesive shown exposed in Fig 1) wherein the portion of the plate under the second chip is enclosed (i.e. adhesive covers 2 vertical sides and top horizontal portion) with an adhesive/underfill and the adhesive layer is exposed at the corner formed by the plate and second chip along the longitudinal side of the plate (Fig 1; shows exposed adhesive/underfill along sides of plate and chip); (cl. 11) further discloses said first chip on the substrate and electrically connected to the substrate by a plurality of electrical leads (19), and said second chip electrically connected to the substrate by a plurality of electrical leads (24) wherein the chips (3, 4) are directly attached to the plate (61) by adhesive (Fig 1; 27, and underfill not labeled; Par, 0038).

Allowable Subject Matter

Claims 5-10 are allowed.

The following is a statement of reasons for the indication of allowable subject matter: the prior art does not disclose or make obvious a plate between a first and second chip, wrapped in an adhesive such that a portion of the adhesive is also between the chip and plate and the plate has a longitudinal length greater than the second chip and the third chip has a longitudinal length greater than the longitudinal length of the plate or that the width of the plate is smaller than that of the second chip including all the limitation of the independent claim.

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Although stacked arrangement of chips and plates that decrease in length from its lower to top component are known as shown in Maeda (JP 3-109760; Fig 1, 2), the present invention is distinguishable in that the plate is not wrapped in an adhesive, whereby more than one surface of the plate is covered with a continuous layer of adhesive and therefore enclosed in an adhesive as shown in applicant's Figure 2. The prior art merely discloses an adhesive on a single surface of a plate and not wrapped in an adhesive.

Response to Arguments

Applicant's arguments with respect to claims 5-10 have been fully considered and are persuasive; therefore, the rejections based on those claims are withdrawn.

Applicant argument with respect to claim 11 is unpersuasive and the rejection maintained.

Applicant contends that chip three and four of Kamei are not adhered to a plate directly by an adhesive. Examiner respectfully disagrees. Because Kamei explicitly discloses the attachment of chips (3, 4) to a plate (61) directly by adhesive (Fig 1; 27, and underfill not labeled; Par, 0038), applicant's arguments are deemed unpersuasive.

Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

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A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to James M. Mitchell whose telephone number is (571) 272-1931. The examiner can normally be reached on M-F 8:00-4:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

CARL WHITEHEAD, JA SUPERVISORY PATENT EXAMINER TECHNOLOGY CENTER 2800